

Title (en)

SOLDER CONTACT AND CONTACT MODULE AND METHOD FOR PRODUCING A CONTACT MODULE

Title (de)

LÖTKONTAKT UND KONTAKTMODUL UND VERFAHREN ZUR HERSTELLUNG EINES KONTAKTMODULS

Title (fr)

CONTACT À SOUDER ET MODULE DE CONTACT ET PROCÉDÉ DE FABRICATION D'UN MODULE DE CONTACT

Publication

EP 3698437 A1 20200826 (DE)

Application

EP 18785607 A 20181011

Priority

- DE 102017124549 A 20171020
- EP 2018077741 W 20181011

Abstract (en)

[origin: WO2019076726A1] A solder contact, having a contact region (4) for the contact-connection of a plug contact (30), having at least one SMD solder surface (6, 8, 10, 12), which is configured for soldering to a printed circuit board (28) and for materially bonded connection to a solder pin (22, 44, 50, 54, 56, 60, 62, 66) and having at least one recess (14, 16, 18), which is configured to receive a solder pin (22, 44, 50, 54, 56, 60, 62, 66).

IPC 8 full level

H01R 12/57 (2011.01); **H01R 12/58** (2011.01); **H01R 13/11** (2006.01); **H01R 43/16** (2006.01)

CPC (source: EP US)

H01R 12/57 (2013.01 - EP US); **H01R 12/58** (2013.01 - EP US); **H01R 43/0235** (2013.01 - US); **H01R 43/0256** (2013.01 - US); **H01R 43/16** (2013.01 - US); **H01R 13/112** (2013.01 - EP); **H01R 43/16** (2013.01 - EP)

Citation (search report)

See references of WO 2019076726A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

DE 102017124549 B3 20190221; CN 111213285 A 20200529; CN 111213285 B 20211231; EP 3698437 A1 20200826; US 2021126387 A1 20210429; WO 2019076726 A1 20190425

DOCDB simple family (application)

DE 102017124549 A 20171020; CN 201880066858 A 20181011; EP 18785607 A 20181011; EP 2018077741 W 20181011; US 201816756991 A 20181011